

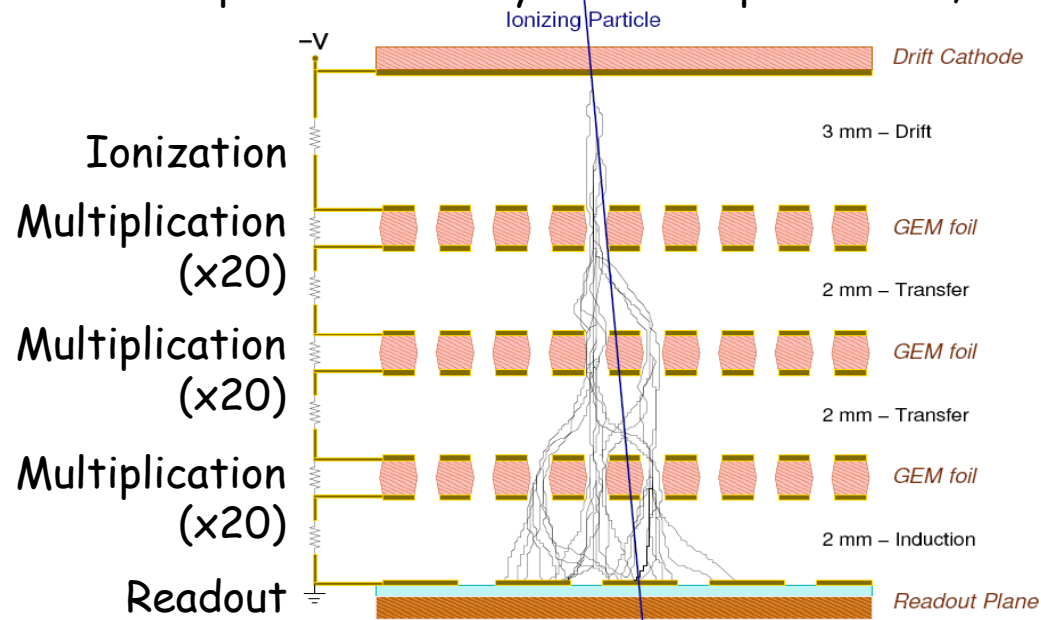
GEM Detectors for SoLID

Nilanga Liyanage and Knodo Gnanvo

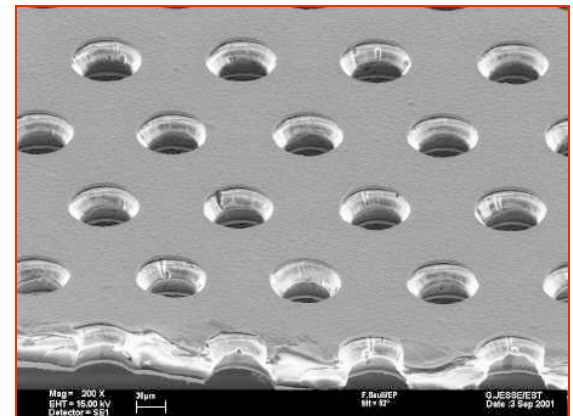
University of Virginia

Why GEMs ?

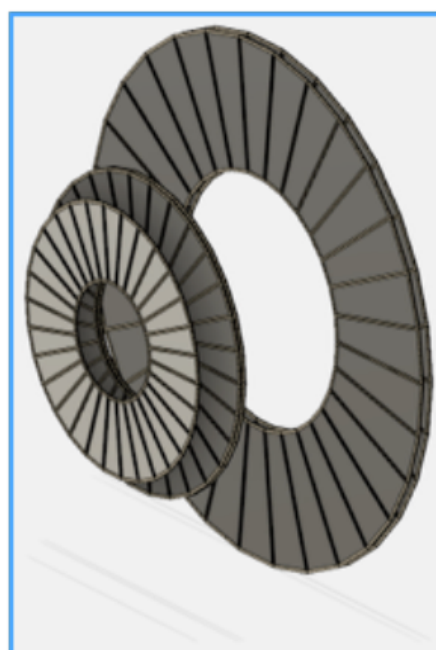
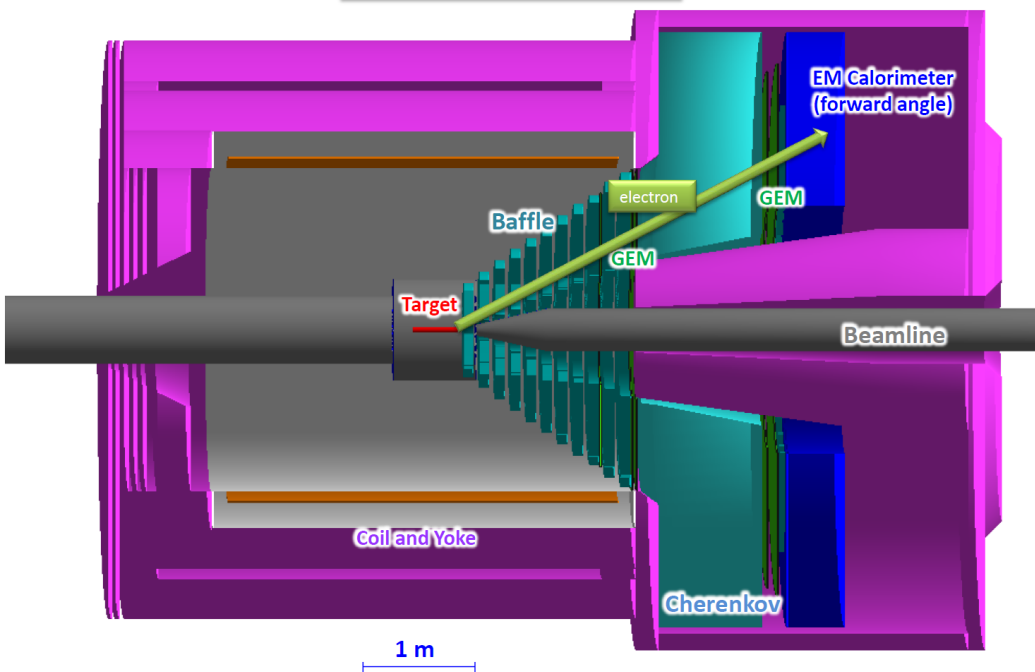
- SoLID concept leads to high rate in trackers: and requires good resolution.
- Gas Electron Multiplier (GEM) detectors provide a cost effective solution for high resolution tracking under high rates over large areas.
 - Rate capabilities higher than many MHz/cm²
 - High position resolution (< 75 μm)
 - Ability to cover very large areas (10s - 100s of m²) at modest cost.
 - Low thickness (~ 0.5% radiation length)
 - Already Used for many experiments around the world: COMPASS, Bonus, KLOE, TOTEM, STAR FGT, ALICE TPC, pRad etc.
 - And planed for many future experiments: CMS upgrade, SoLID, Moller, P2 @ Mainz



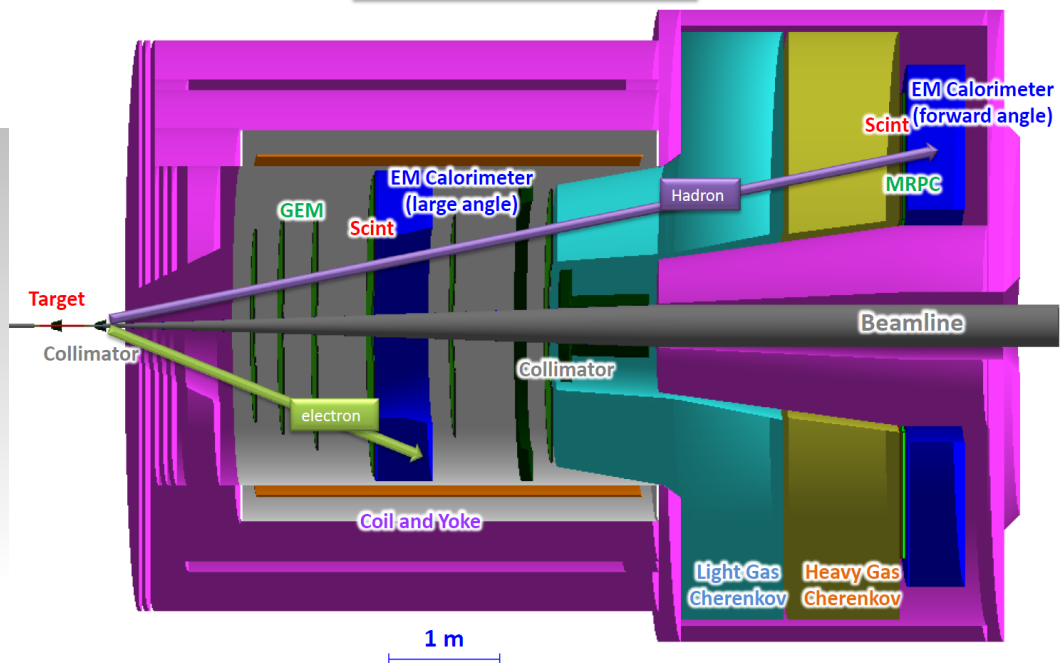
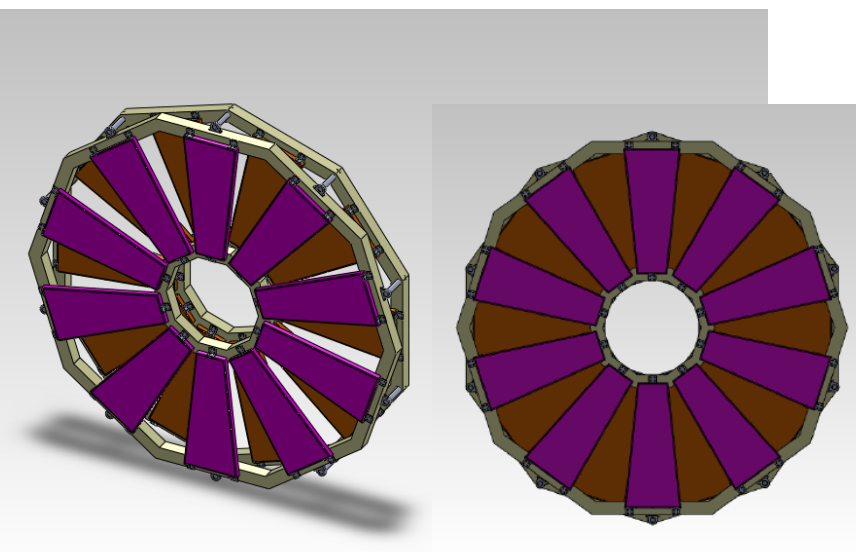
GEM foil: 50 μm Kapton + few μm copper on both sides with 70 μm holes, 140 μm pitch



SoLID (PVDIS)



SoLID (SIDIS & J/ψ)



Major change in plans since last meeting

- Separated into baseline equipment and enhancements
 - Baseline:
 - Only GEM layers 1, 3, 4,5 for SIDIS: built by the UVa group
 - Reuse electronics from SBS and TDIS
 - Enhancements
 - GEM layers 2 (and 6 ?): Funded and Built by the Chinese collaboration
 - New electronics for these two layers and to replenish others

Plane	Z (cm)	R _I (cm)	R _O (cm)	Active area (m ²)	# of channels
1	-175	36	87	2.0	24 k
2	150	21	98	2.9	30 k
3	-119	25	112	3.7	33 k
4	-68	32	135	5.4	28 k
5	5	42	100	2.6	20 k
6	92	55	123	3.8	26 k
total:				~20.4	~ 161 k

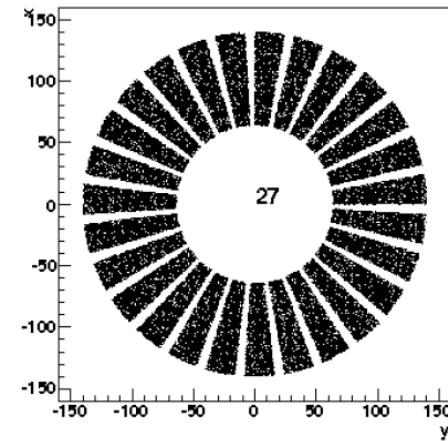


105 k channels
Needed for baseline

SIDIS GEM full configuration

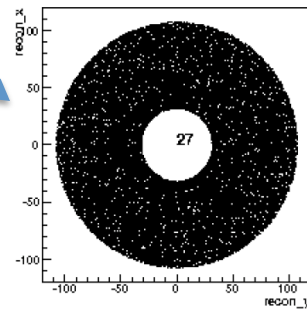
- Six locations instrumented with GEM:
- PVDIS GEM modules can be re-arranged to make all chamber layers for SIDIS. - move the PVDIS modules closer to the axis so that they are overlapping with each other

Plane	Z (cm)	R _I (cm)	R _O (cm)	Active area (m ²)	# of channels
1	-175	36	87	2.0	24 k
2	-150	21	98	2.9	30 k
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4	-68	32	135	5.4	28 k
5	5	42	100	2.6	20 k
6	92	55	123	3.8	26 k
total:				~20.4	~ 161 k



PVDIS

SIDIS



- More than enough electronic channels from PVDIS setup.
- The two configurations will work well with no need for new GEM or electronics fabrication.

PVDIS GEM full configuration

- Instrument five locations with GEMs:
- 30 GEM modules at each location: each module with a 12-degree angular width.

Location	Z (cm)	R_{min} (cm)	R_{max} (cm)	Surface (m ²)	# chan
1	157.5	51	118	3.6	24 k
2	185.5	62	136	4.6	30 k
3	190	65	140	4.8	36 k
4	306	111	221	11.5	35 k
5	315	115	228	12.2	38 k
Total				≈ 36.6	≈ 164 k

Largest GEM module size required: 113 cm x (21-44) cm

With ~5% spares, we will need about 170 k readout channels.

- Large number of readout channels; but cost of electronics going down - cost per channel for the RD51 SRS APV-25 based readout is $\sim \$ 3.00$ + R&D expenses to optimize electronics for SoLID needs.

"PVDIS" GEM baseline configuration

- We can cover the 4 baseline SIDIS layers with layers 1, 3 and 4 of PVDIS.

Location	Z (cm)	R_{min} (cm)	R_{max} (cm)	Surface (m ²)	# chan
1	157.5	51	118	3.6	24 k
2	185.5	62	136	4.6	30 k
3	190	65	140	4.8	36 k
4	306	111	221	11.5	35 k
5	315	115	228	12.2	38 k
Total				≈ 36.6	≈ 164 k

- Need 90 modules of 3 sizes ~ 70 cm, ~ 80 cm, ~ 110 cm.
- With 10% spares for each size \Rightarrow 99 modules total over 4 years.
- Well within the capabilities of the UVa group.
 - Built 48 large modules for SBS.
 - @ ~ 20 production modules per year.
 - could double to rate with the person-power requested for SoLID

Baseline Plan for electronics

- Need 105 k channels + 10% spares ~ 115 k chan.
- Reuse from SBS (APV-25) and TDIS (SAMPA)
- SBS will have a total of ~ 155 k of APV-25 (115 k chans. owned by Jlab (from UVA) ~ 40 k owned by INFN).
 - Assuming that we can get these all and ~ 66% survival rate after SBS run, we will have ~ 102 k of APV electronics for SoLID
- TDIS will have 27.5 chan. of SAMPA.
 - Assuming 66% survival: will have 18.k k chans. for SoLID.
 - Sufficient for base line.
 - **Warning: SAMPA is not rad-hard**
- No electronics funding in the baseline plane: only 0.5 FTE-year at Jlab for reconfiguring the old electronics for SoLID.
- Also assume reusing all upstream electronics modules (SSPs etc, transducers); but these will be obsolete by then and will require replacing.

Ongoing work carried out by Kondo supported by EIC R&D.

- A new EIC prototype GEM with many new features successfully developed.
 - Moving all readout connections to the outer edge of the circle:
 - successfully demonstrated with small prototype, now implemented in full size module.
- Composite frames: will reduce cost for SoLID
- beam tested at Fermilab last summer
- uRwell prototype
- Planning for a 1 k channel VMM based SRS test stand

EIC Low Cost Frames

Total set of pieces for all 4 frames



Set of 3 pieces for 1 frame



pieces fit together to form a frame



Large & Low-mass Forward Tracker GEM for EIC R&D

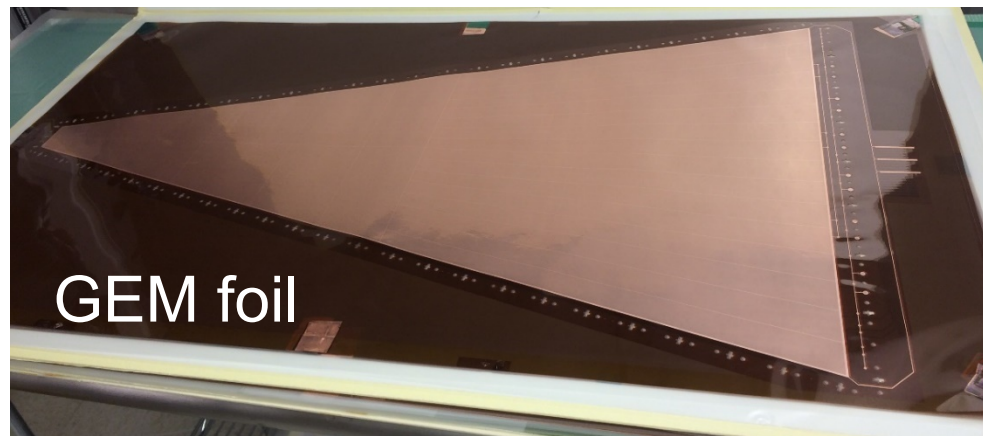


Going to the test beam at Fermilab FTBF in two weeks from now

Large & Low-mass Forward Tracker GEM for EIC R&D

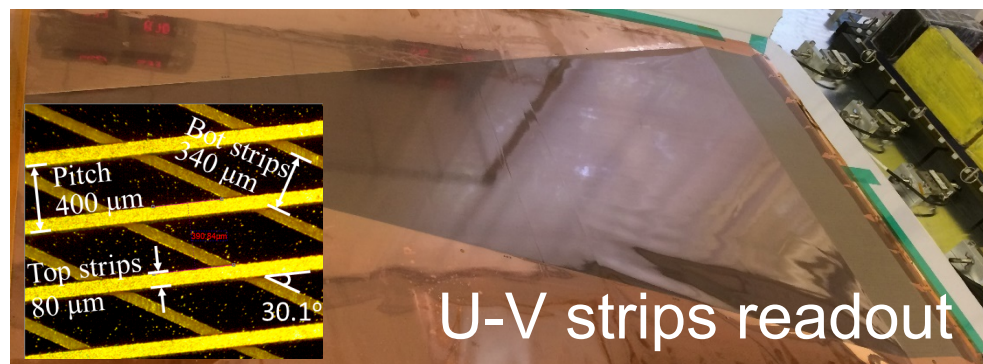
Common GEM foil design:

- (Univ. of Virginia, Florida Tech, and Temple U.)
- All connections (HV, gas flow structure and FE cards) are made on outer radius end.



2D U-V strips readout (R/O)

- Spatial resolution improvement
- All readout electronics on outer radius end.
- No connectors or metallized vias on R/O

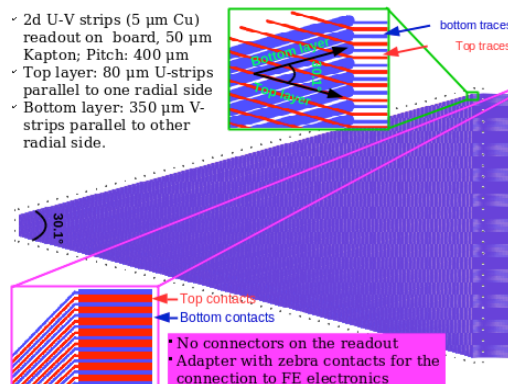


Double-sided zebra connection

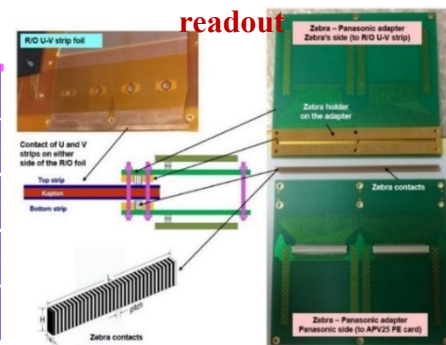
- Large density of electronics channels read out on side of the detector (outer radius)
- No electronics on side or inner radius, no multiple scattering or radiation damage issues
- No connectors or metallized vias on R/O

Design of EIC-Proto II 2D U-V strips readout board

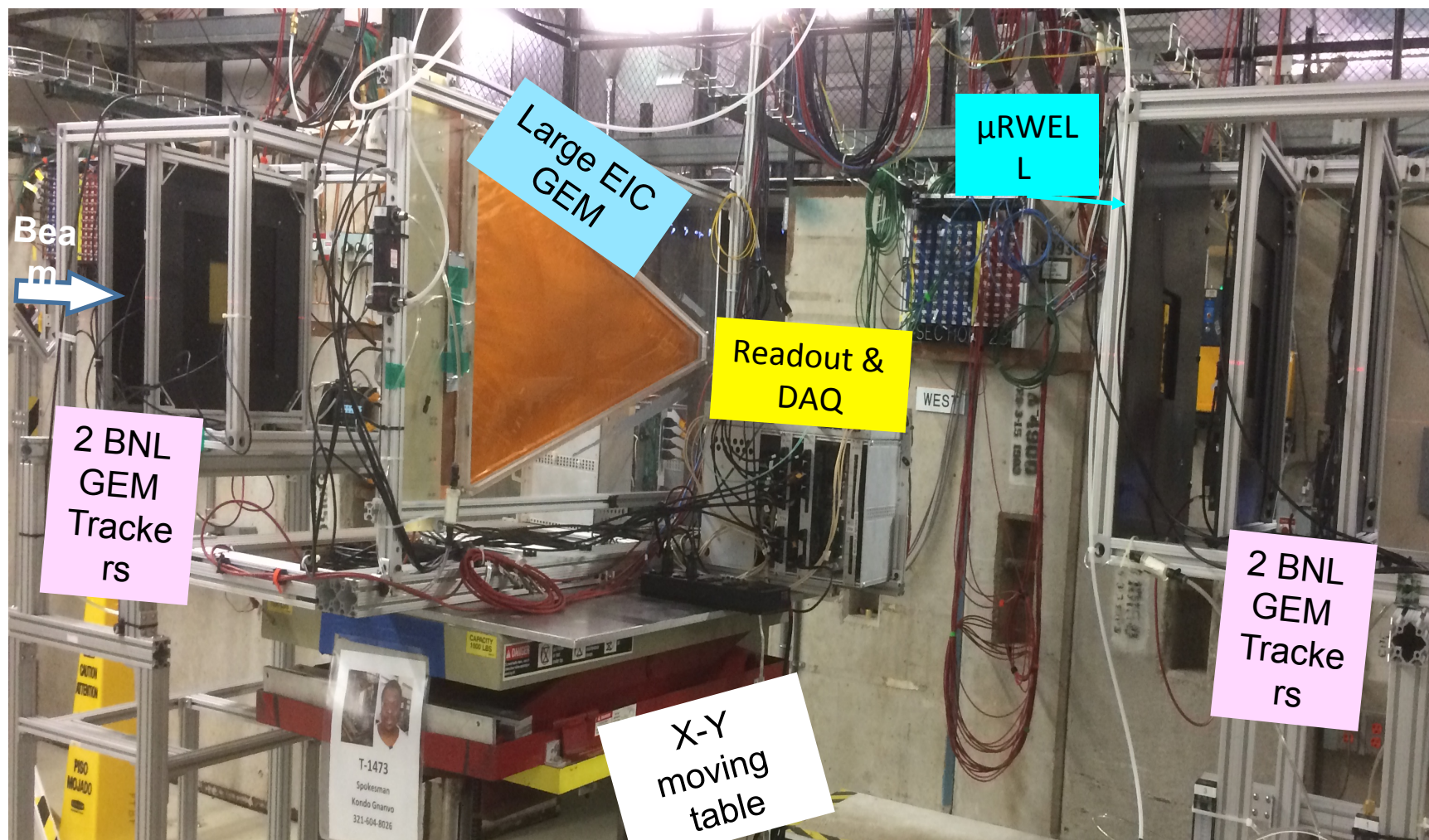
- ✓ 2d U-V strips (5 μm Cu) readout on board, 50 μm Kapton; Pitch: 400 μm
- ✓ Top layer: 80 μm U-strips parallel to one radial side
- ✓ Bottom layer: 350 μm V-strips parallel to other radial side.

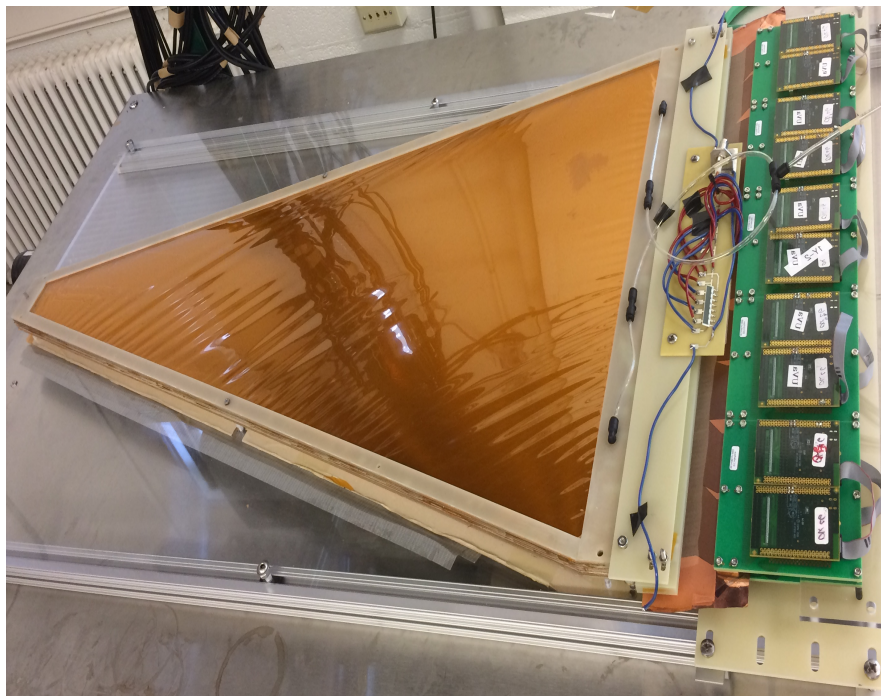


Principle of double-sided zebra connection on flexible PCB readout

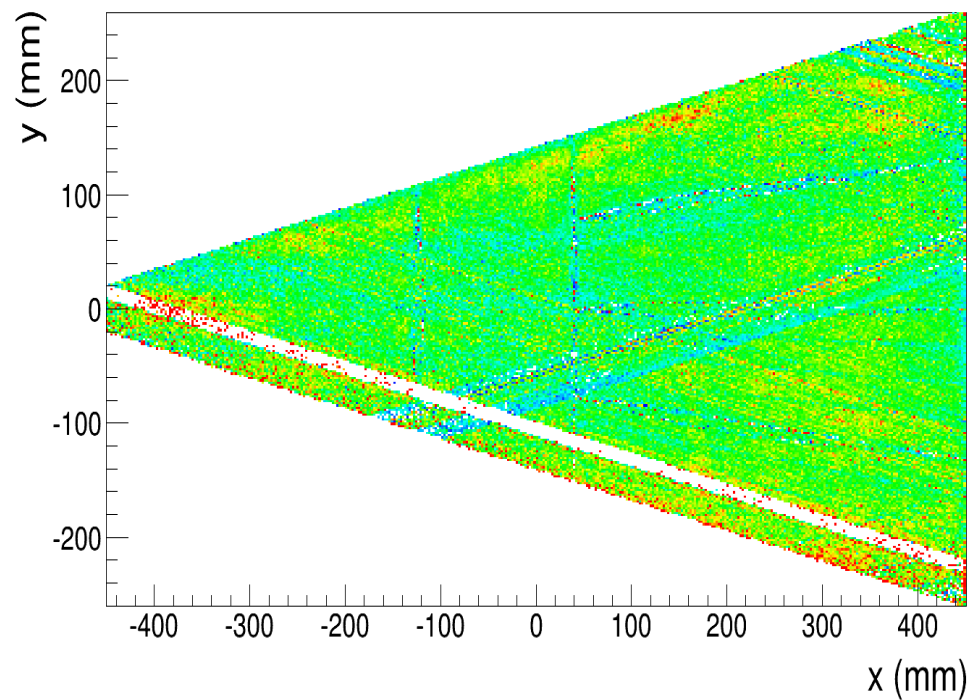


Large GEM Setup in MT6.2b Area at the FTBF (June-July 2018)

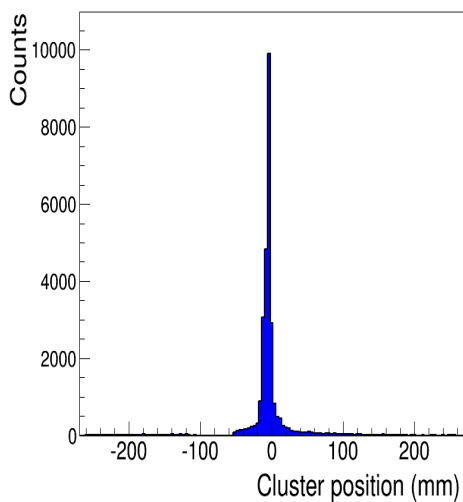




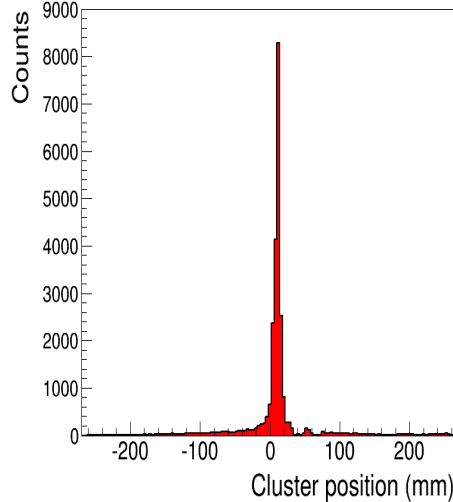
EIC-FT-GEM : Gain uniformity with Cosmics - Average ADC counts



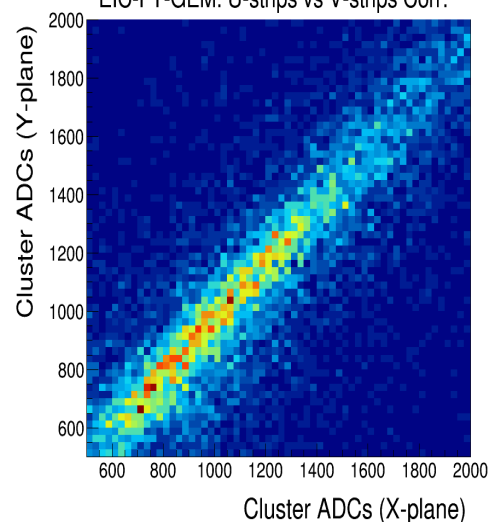
EIC-FT-GEM (U-Strips): 120 GeV Proton



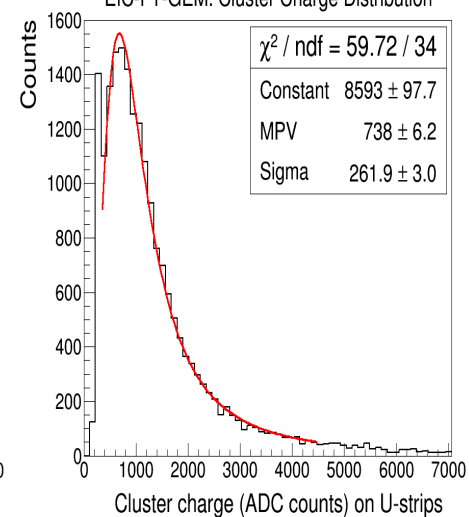
EIC-FT-GEM (V-Strips): 120 GeV Proton



EIC-FT-GEM: U-strips vs V-strips Corr.

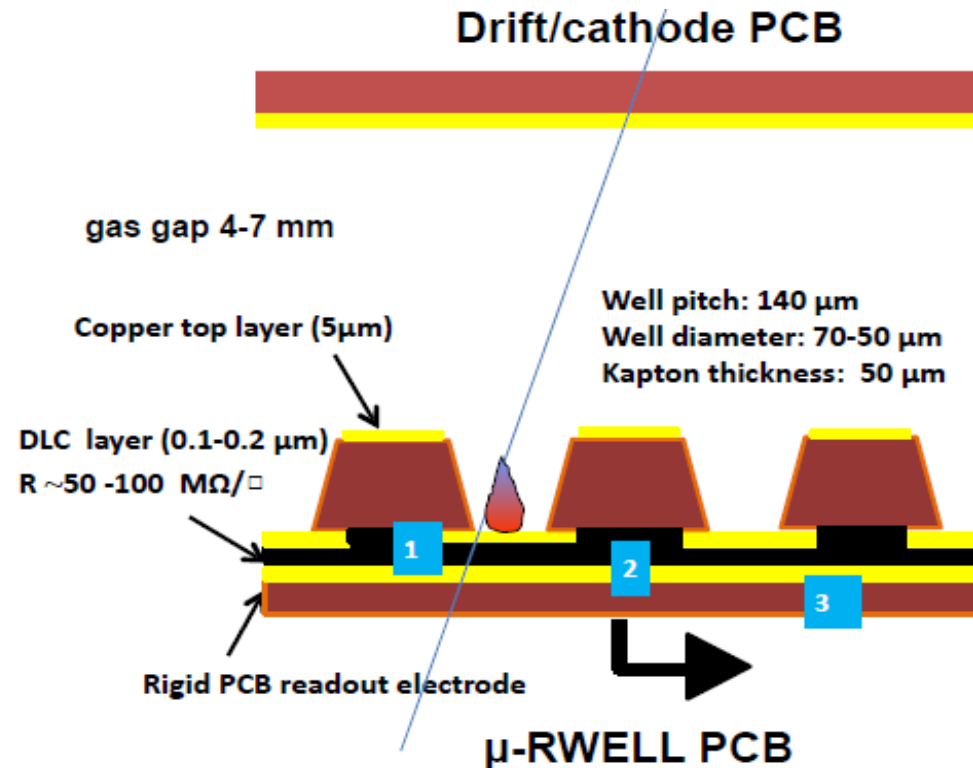


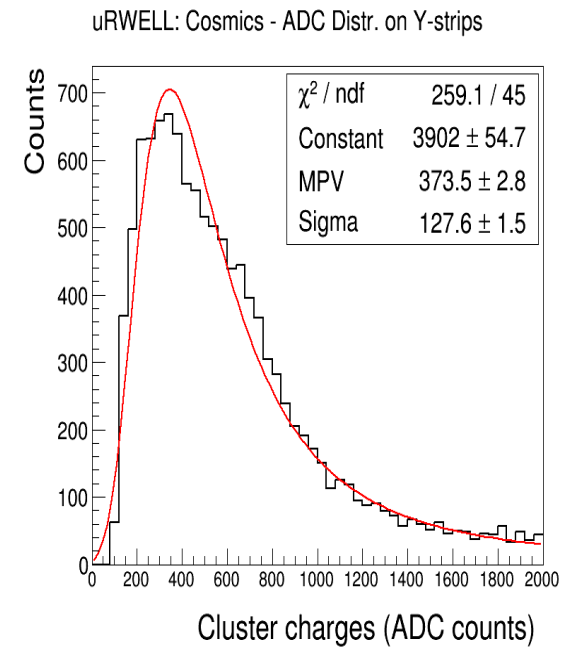
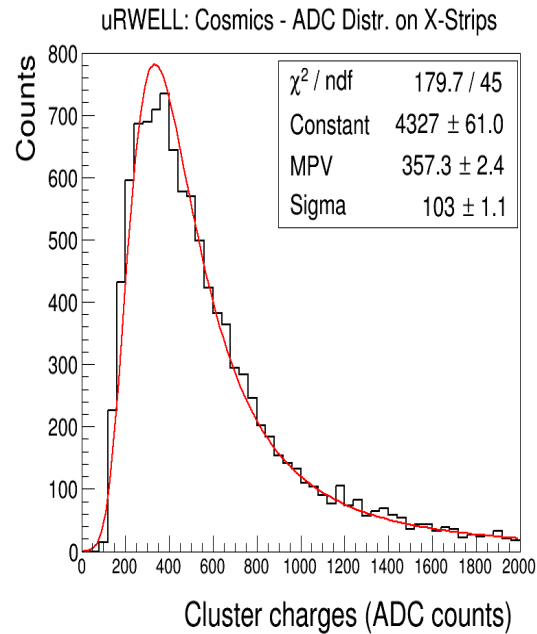
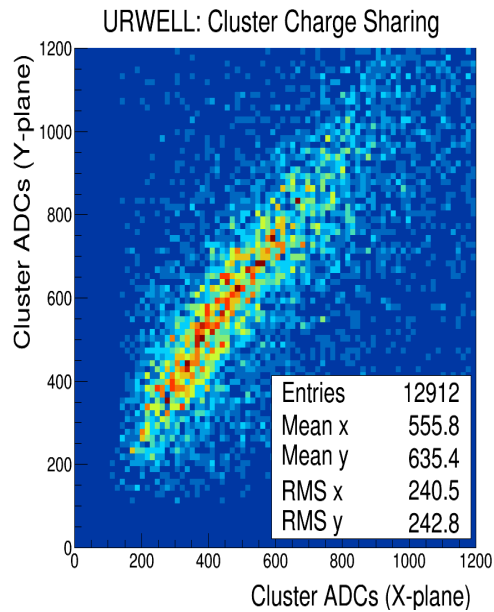
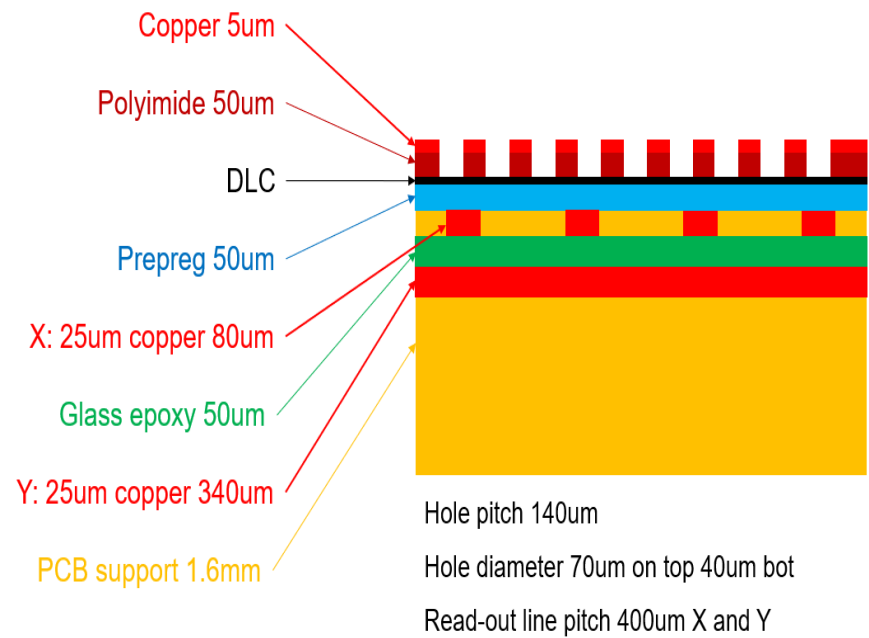
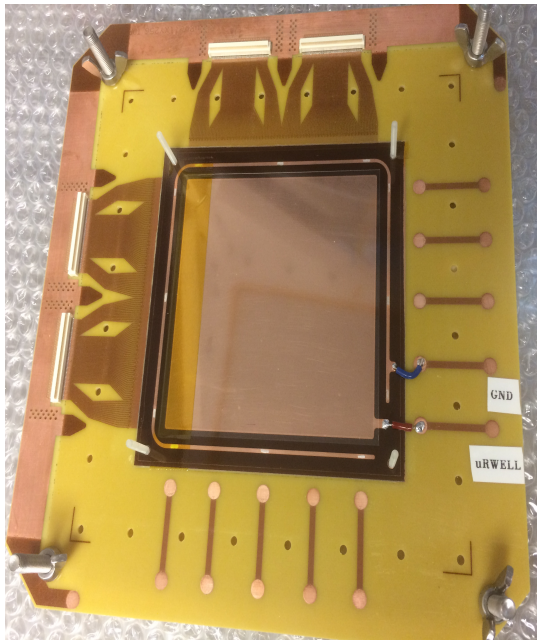
EIC-FT-GEM: Cluster Charge Distribution



Ongoing work carried out by Kondo supported by EIC R&D.

- Development of μ -RWELL detectors:
 - combines GEM and readout together
 - much lower cost
 - can work up to $\sim 100 \text{ kHz/cm}^2$.





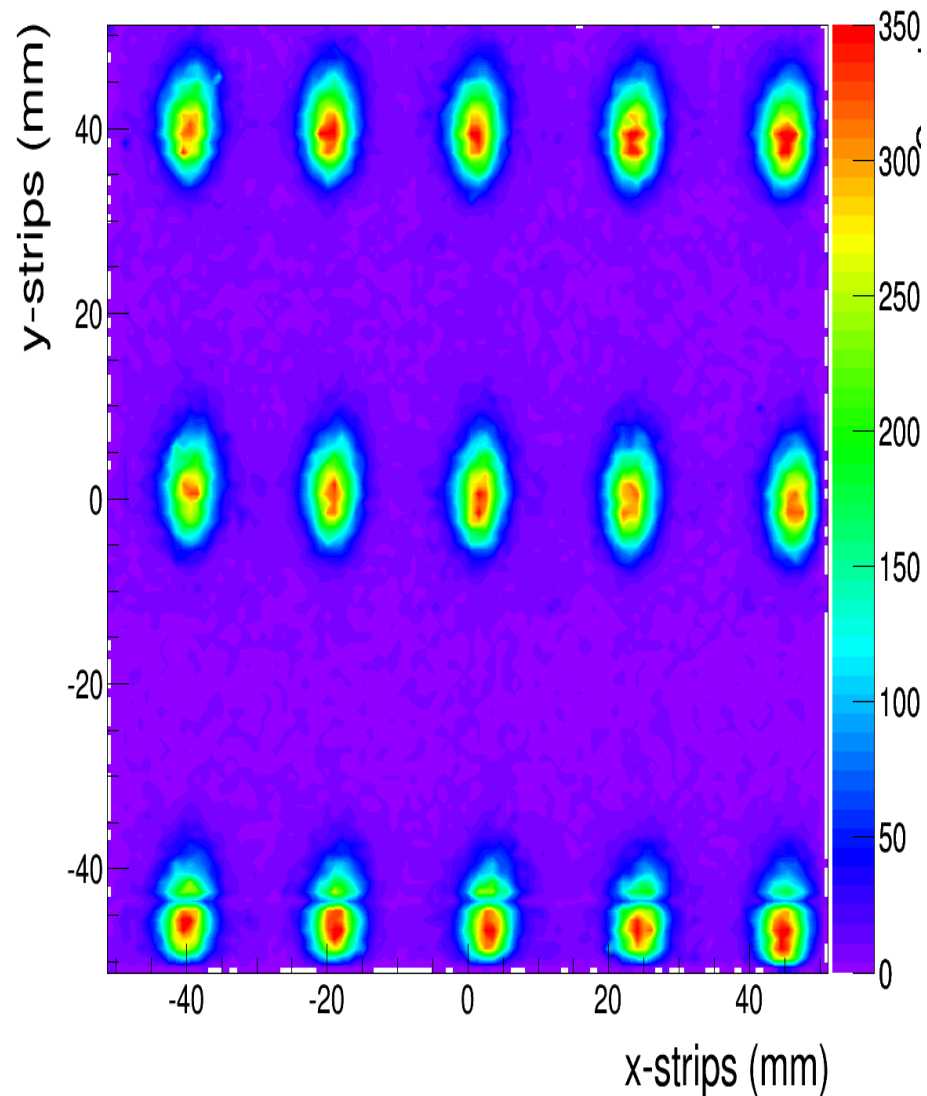
Small Prototypes Setup (FTBF June- July 2018)

μ RWE
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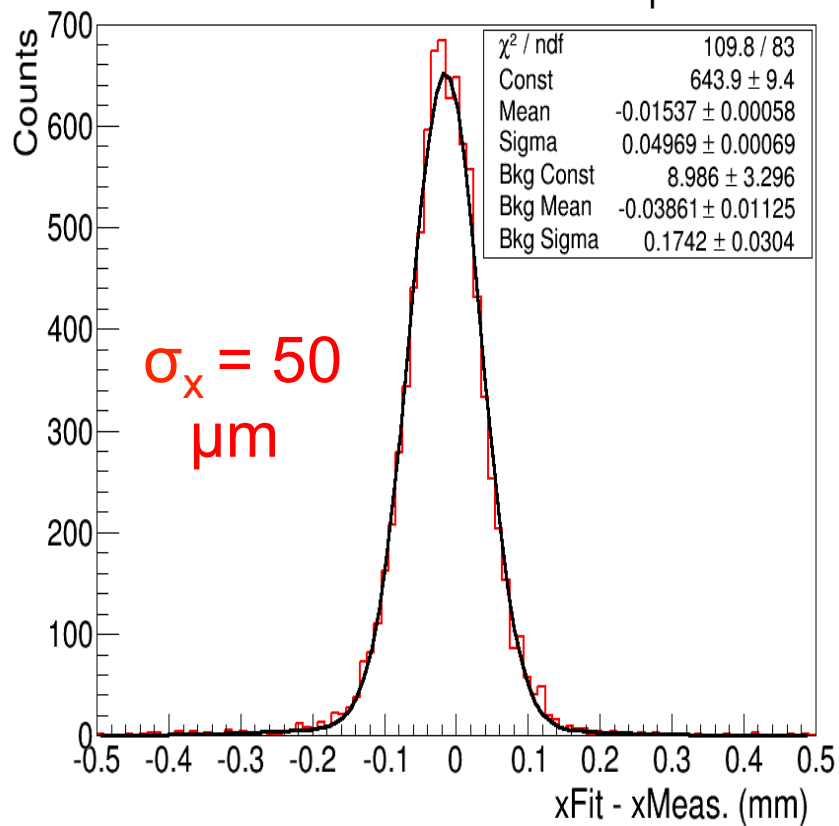
2D ZZ
GEM
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Large
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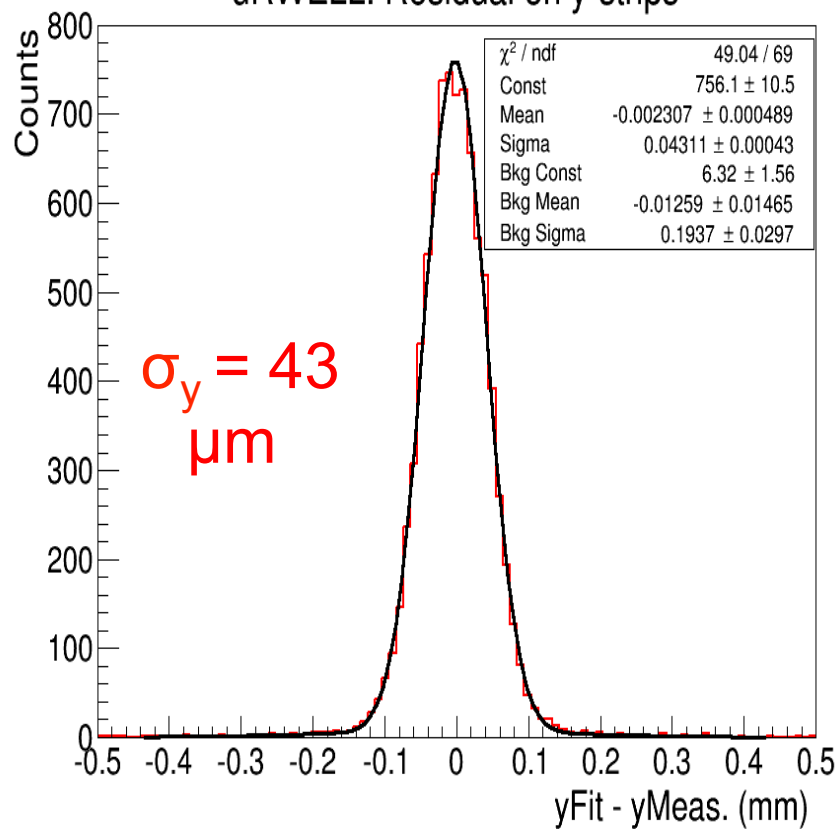
uRWELL: Hit Position Map



uRWELL: Residual on x-strips



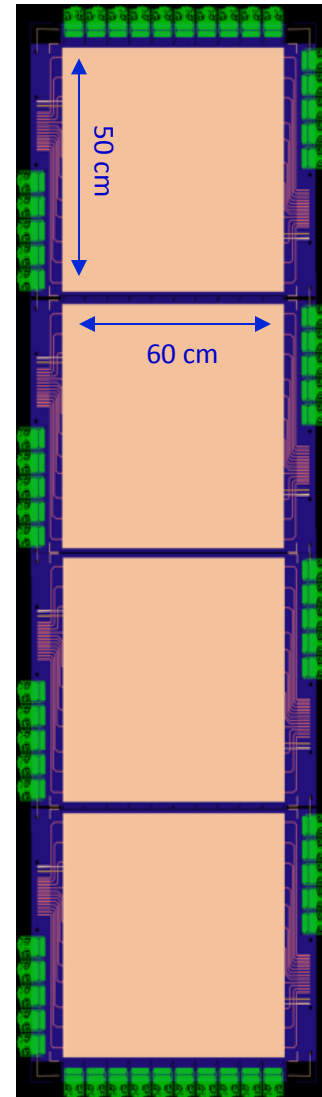
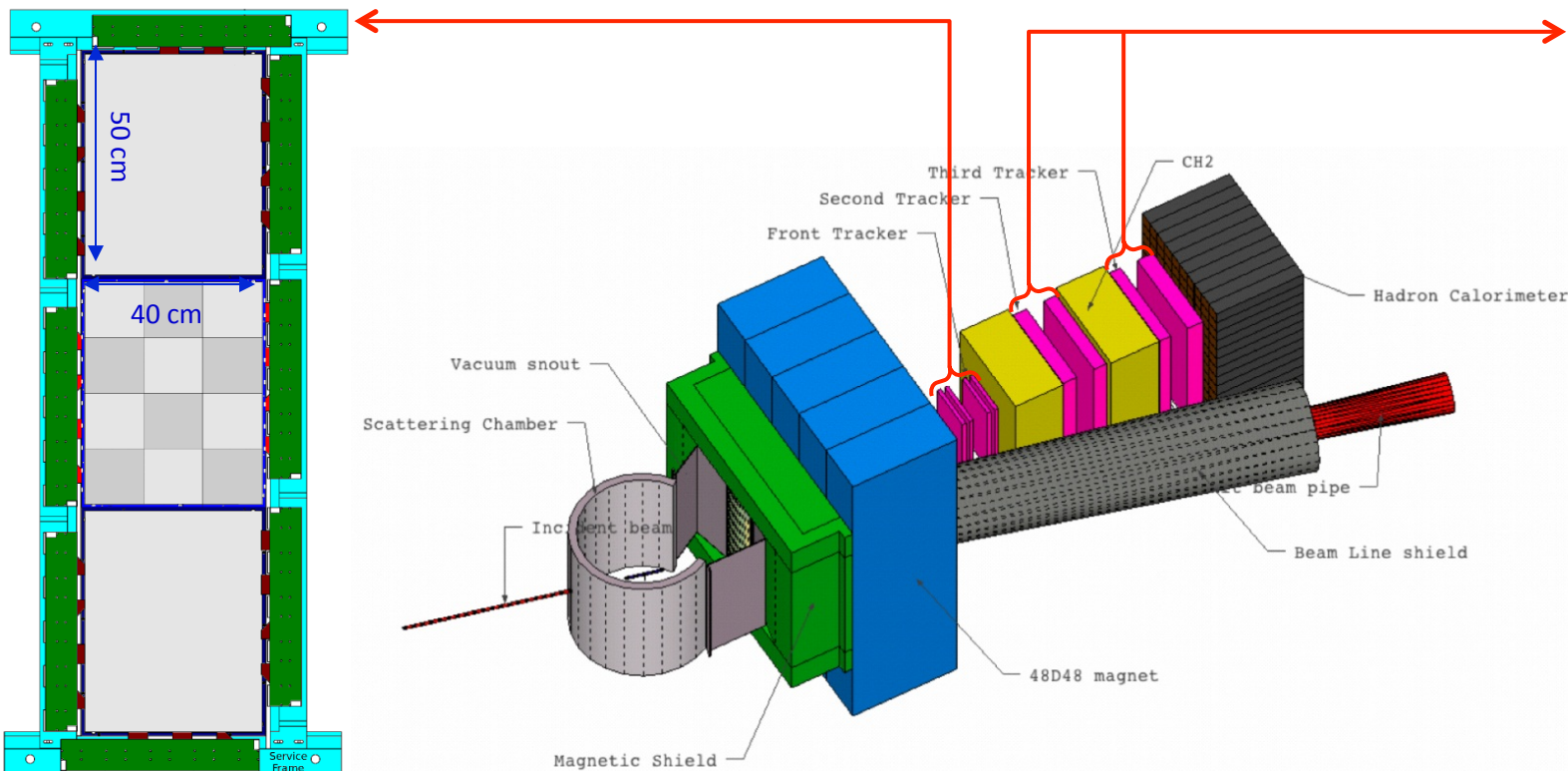
uRWELL: Residual on y-strips



GEM Trackers for SBS

- **Front Tracker:**
- 6 GEM Layers ($150 \times 40 \text{ cm}^2$)
- Each layer = 3 GEM modules ($50 \times 40 \text{ cm}^2$)
- R&D and Production by INFN Roma, Catania

- **Back Tracker**
- 10 GEM Layers ($200 \times 60 \text{ cm}^2$)
- Each Layer = 4 GEM modules ($50 \times 60 \text{ cm}^2$)
- R&D and Production @ University of Virginia



Proton arm layout for GEp (5) experiment

Total Area $\sim 16 \text{ m}^2$

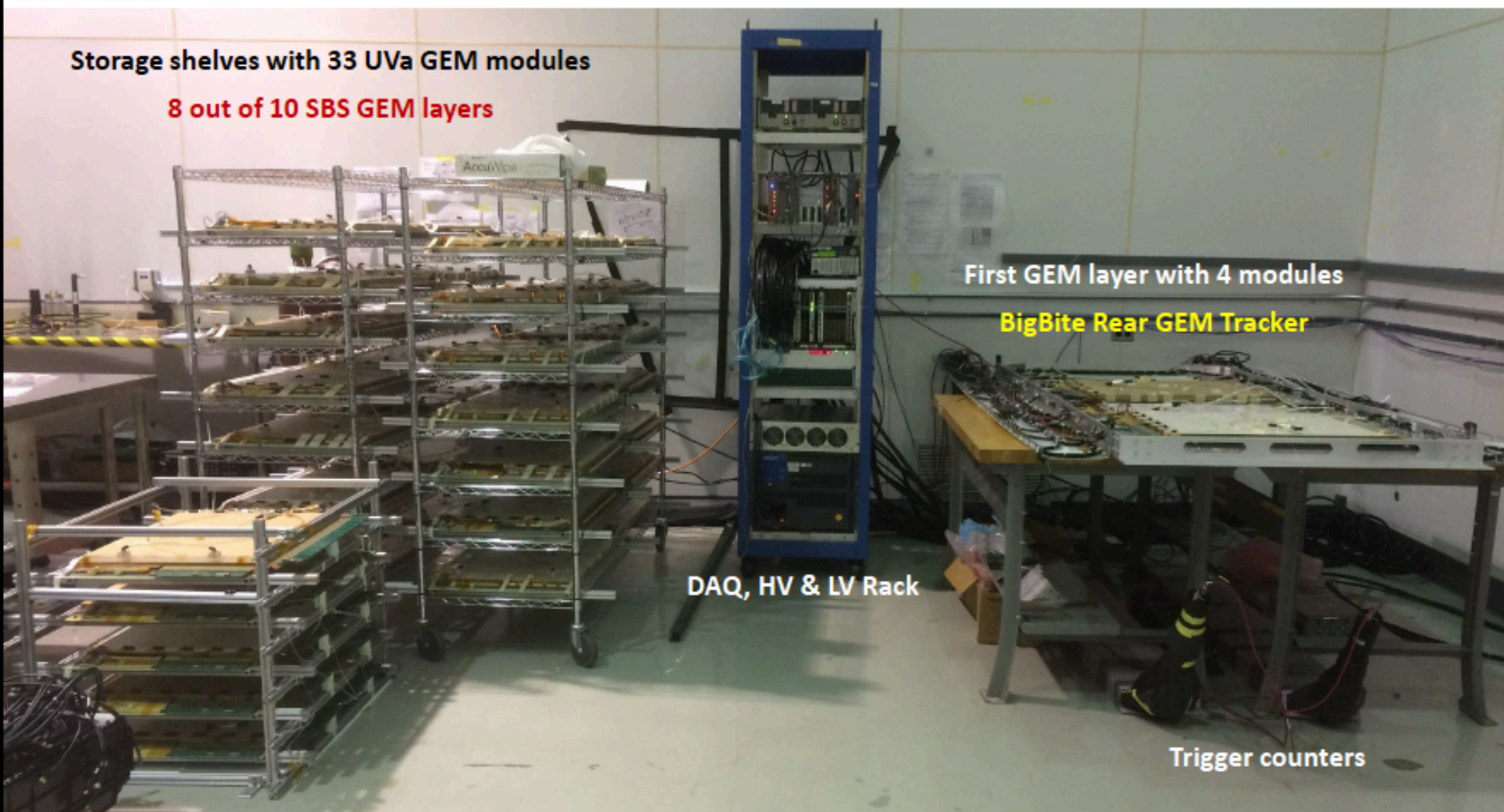
SBS GEM Production complete

- Completed building 48 modules (plan was to build 40) and tested.
- 46 tested modules and all work per specs.
- Foils from CERN very high quality; over 90% yield; mostly on-time delivery.
- Foil QA at every step extremely important.

Ongoing work for SBS GEMs

- Installation of GEM modules into layers now
- Installation and testing of all electronics.
- Working with DAQ group to implement hardware level data reduction.
 - common mode correction
 - pedestal subtraction
 - zero suppression
 - filter out background not correlated with trigger time.
- Working on GEM background suppression and tracking for GMn experiment conditions (rates ~ 100 kHz/cm²)

Status of UVa GEMs for SBS (EEL Clean Room 124)



Storage shelves with 33 UVa GEM modules

8 out of 10 SBS GEM layers

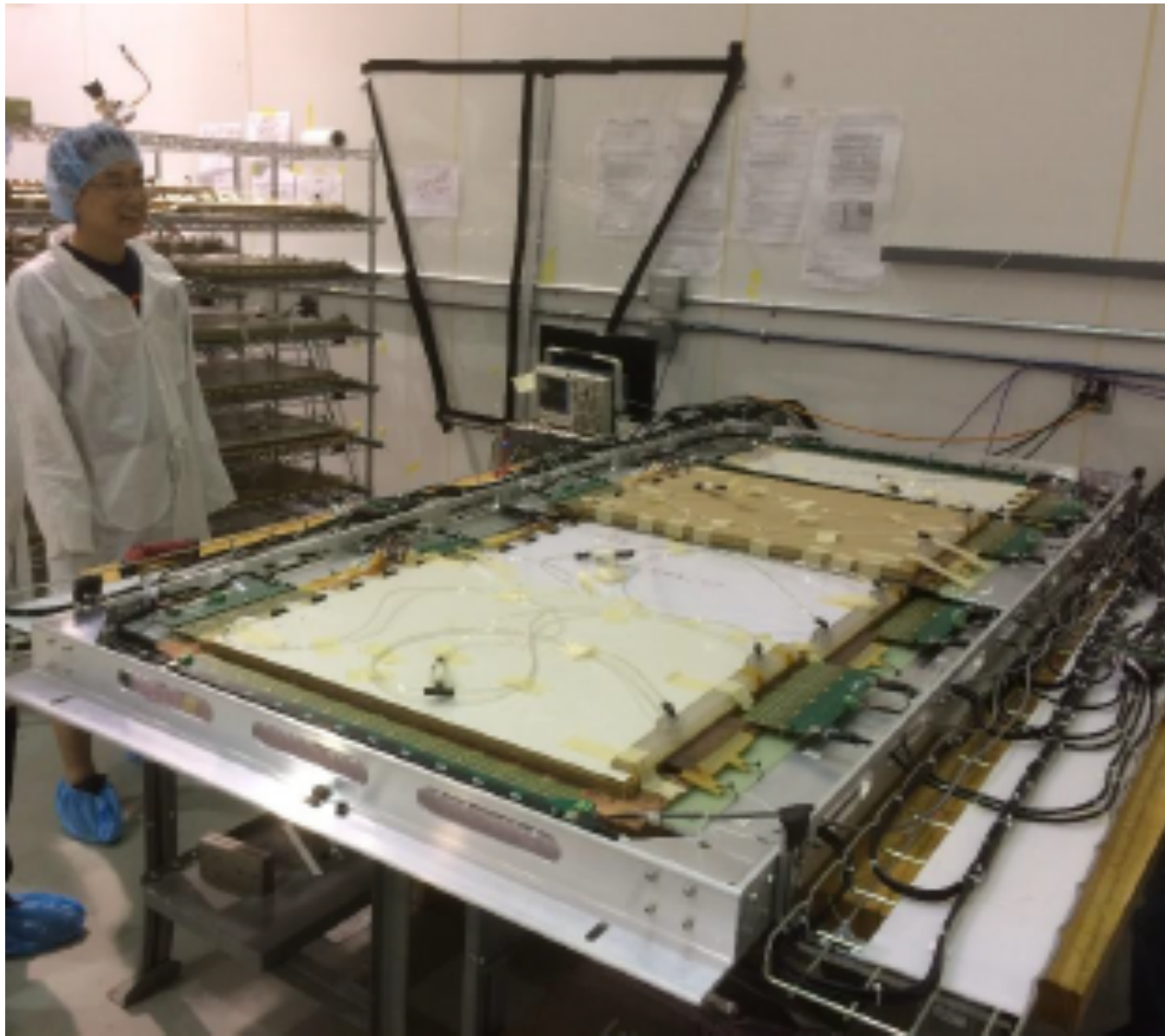
First GEM layer with 4 modules

BigBite Rear GEM Tracker

DAQ, HV & LV Rack

Trigger counters

- 37 Modules for 9 SBS GEM layers already in store at JLab (EEL Clean Room 124)
- Additional 7 modules (+ spares) for 2 remaining layers to be shipped to JLab in the coming weeks (~November 2018)
- 2 INFN SBS GEM layers to be assembled / tested in Testlab CL after 4 INFN BB GEMs installed in BB in TED (Summer 2019)



Alternate Chip Options

- VMM3: Developed by BNL for ATLAS
 - Good
 - digital output with on board zero suppression
 - High rates
 - suitable for large detectors,
 - Bad
 - single sample; does not allow pileup correction or time based background rejection

Alternate Chip Options: VMM

APV_(ANALOGUE)

APV (250 nm CMOS)

- Pipeline depth: max. 192 clocks
- Trigger latency: max. 3 us
- Noise: < 500 e- intrinsic >750..1400 e- on detector
- dynamic range: 25 fC
- Detector capacity: 18... < 60pf
- ADC ext. 4096/1000 [counts/baseline]
- Gain: fixed CSA gain 100uA/mip, 5 output signal gains (in step of 20%)
- Timing jitter : $\frac{1}{2} (1/f_c)$ [+ - 12ns]
- Shaping times: 50 ns adjustable to 80 ns
- max readout rate: 7 kHz

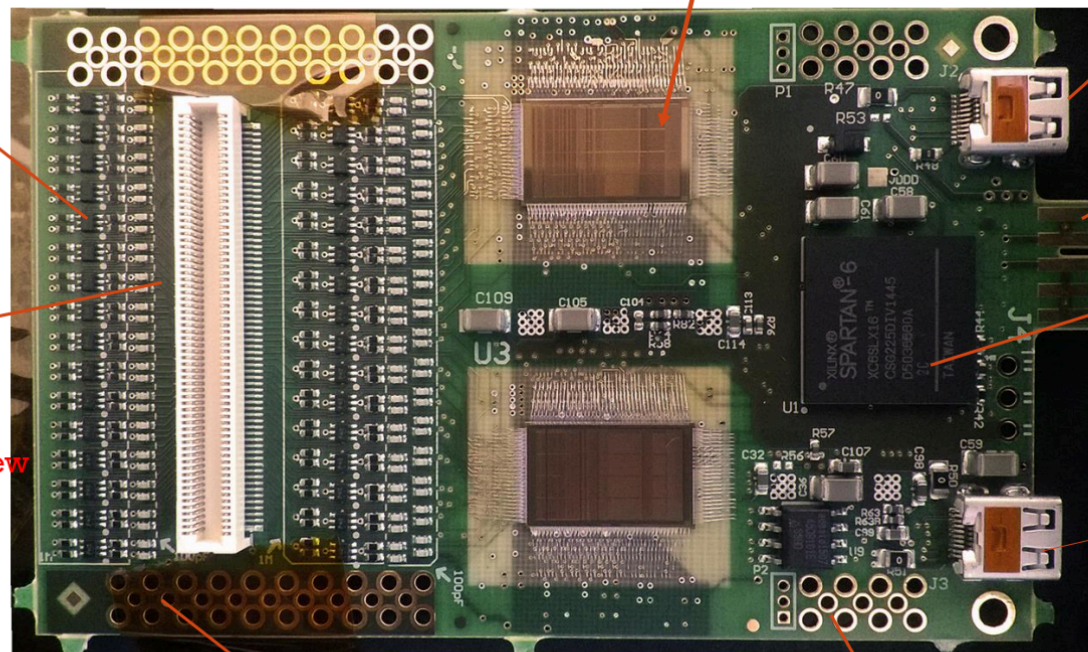
VMM_(DIGITAL)

VMM (130nm CMOS)

- Pipeline depth: 64 digital frames (peak)
- Trigger latency: (self triggered) or L0 (12.8us)
- noise : < 400 e- on 10x10 detector reported
- dynamic range: expect >> 25 fC
- Detector capacity: 30pF < 1nF
- ADC: embedded, 10 bit
- Gains: 8 CSA gains [0.5..16mV/fC]
- Timing jitter: 20 bit t-stamp, 1ns resolution
- Shaping times: 4 [25... 200ns]
- max readout rates: estimated 4 MHz/ch

Alternate Chip Options: VMM: SRS version

Photo: 2 x wire-bonded VMM2 chips -> new VMM3 board fully routed



AC coupling
&
spark protection

HDMI link 1 DTCCP

JTAG

Companion FPGA

HDMI link 2 DTCCP

Detector GND MMCx

Neighbor-channel via MMCX

Panasonic 130 pin
connector for MPGDs
Will be replaced by new
140 pin HRS connector